

ABSTRACT OF THE DISCLOSURE

5 The present invention provides a packaged substrate which has a superior positioning accuracy of wiring formed on a circuit substrate made of ceramics, and a conductive pattern with a thick film and yet a fine pattern.

10 On a surface of flexible base member made of plastic, fine grooves are formed in a pattern corresponding to a first conductive pattern so that a cavity face is produced. Conductive paste is filled and into the grooves on this cavity face, and then dried. The cavity face and a circuit substrate are pasted with each other by applying predetermined heat and pressure. A pattern of the dried conductive paste is transcribed onto the circuit substrate, and then the first
15 conductive pattern is formed by firing. A first ball solder is coupled with a second conductive pattern which is coupled to the first conductive pattern through an electrode in a through-hole of the circuit substrate.